

L Number	Hits	Search Text	DB	Time stamp
3	165832	438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:22
5	137	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with recipe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:23
6	53	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initializ\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:28
7	493	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initial\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:32
8	494	((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initializ\$3)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initial\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:34
9	20	((((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initializ\$3)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initial\$4))) and ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with recipe))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:28
10	2203	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with (set\$3 or prepar\$5 or format\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:34
11	2357	((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initializ\$3)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initial\$4)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with (set\$3 or prepar\$5 or format\$4))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:35
12	80	((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with recipe)) and (((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initializ\$3)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initial\$4)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with (set\$3 or prepar\$5 or format\$4))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 19:12
13	1	(((((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initializ\$3)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initial\$4))) and ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with recipe)))) and (272434.ap.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 18:55

14	60	((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with recipe)) and (((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initializ\$3)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initial\$4)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with (set\$3 or prepar\$5 or format\$4)))) not (((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initializ\$3)) or ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with initial\$4))) and ((438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with recipe)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/28 19:12
-	3	824301.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 21:39
-	136695	438/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 21:40
-	23504	702/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 21:48
-	5679	700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 21:49
-	84225	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 21:56
-	2347	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with (recipe or control\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 21:57
-	5755	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (etch\$3 and polish\$3 and deposit\$3 and (stepper or \$lithography))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:00
-	7809	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((dummy or test or standard or calibration or reference or pilot) with wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:02
-	219	(438/\$.cccls. or 702/\$.cccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (red-blue or (red adj blue))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:03

	0	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with (recipe or control\$4))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (etch\$3 and polish\$3 and deposit\$3 and (stepper or \$lithography))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((dummy or test or standard or calibration or reference or pilot) with wafer)) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (red-blue or (red adj blue))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:04
	0	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (etch\$3 and polish\$3 and deposit\$3 and (stepper or \$lithography))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((dummy or test or standard or calibration or reference or pilot) with wafer)) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (red-blue or (red adj blue))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:04
	19	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((dummy or test or standard or calibration or reference or pilot) with wafer)) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (red-blue or (red adj blue))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:04
	0	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (etch\$3 and polish\$3 and deposit\$3 and (stepper or \$lithography))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((dummy or test or standard or calibration or reference or pilot) with wafer)) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (red-blue or (red adj blue))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:14

-	85	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with (recipe or control\$4))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (etch\$3 and polish\$3 and deposit\$3 and (stepper or \$lithography))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((dummy or test or standard or calibration or reference or pilot) with wafer)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:50
-	14	((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((semi-conductor or (semi adj conductor) or semiconductor or wafer or (integrated adj (circuit or chip)) or IC) with (manufactur\$3 or product\$3 or fabricat\$3))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (tool with (recipe or control\$4))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and (etch\$3 and polish\$3 and deposit\$3 and (stepper or \$lithography))) and ((438/\$.ccls. or 702/\$.ccls. or 700/29-31,46,52,93,95-97,108-110,117,119,121-123,160,174-178.ccls.) and ((dummy or test or standard or calibration or reference or pilot) with wafer))) and (tool with recipe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/13 22:50